



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: David M. Curran, et al.

Docket No: TI-29038

Serial No: 10/029,788

Conf. No: 5683

Examiner: Timothy V. Eley

Art Unit: 3724

Filed: 10/26/2001

For: METHOD FOR REDUCING THE THICKNESS OF SPIN-ON GLASS ON
SEMICONDUCTOR WAFERS

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OCT 16 2003

TECHNOLOGY CENTER R3700

AMENDMENT UNDER 37 C.F.R. § 1.111

Commissioner For Patents
P.O. Box 1450
Alexandria, VA 22313-1450

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(a)
I hereby certify that the above correspondence is being
deposited with the U.S. Postal Service with sufficient postage
as First Class Mail in an envelope addressed to:
Commissioner for Patents, P.O. Box 1450, Alexandria, VA
22313-1450 on 10-10-03.

Ann Trent
Ann Trent

Dear Sir:

Responsive to the Office Action mailed July 14, 2003, in connection with the
above identified application, Applicants respectfully submit the following amendments
and remarks.